

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A film deposition apparatus comprising:

a stock chamber for loading or unloading a substrate;

a transferring chamber including a first mechanism for transferring said substrate; and

a liquid phase film deposition chamber connected to said transferring chamber through a gate,

wherein said liquid phase film deposition chamber is provided with a second mechanism for oxidizing an element belonging to Group 1 or 2 of the periodic table,

wherein said second mechanism includes an oxidization cell having a lid and an oxygen gettering agent,

wherein a period of time in which said oxygen gettering agent is oxidized is adjusted ~~encapsulated~~ by opening and closing said lid.

2. (Original) A film deposition apparatus according to claim 1,

wherein an inside of said transferring chamber is kept under a reduced pressure and said liquid phase film deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

3. (Original) A film deposition apparatus according to claim 1,

wherein said transferring chamber is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

4. (Currently Amended) A film deposition apparatus comprising:

a stock chamber for loading or unloading a substrate;

a transferring chamber including a first mechanism for transferring the substrate; and

a liquid phase film deposition chamber connected to said transferring chamber through a gate,

wherein said liquid phase film deposition chamber is provided with, via a piping, a second mechanism for oxidizing an element belonging to Group 1 or 2 of the periodic table,

wherein said second mechanism includes an oxidization cell having a lid and an oxygen gettering agent,

wherein a period of time in which said oxygen gettering agent is oxidized is adjusted ~~encapsulated~~ by opening and closing said lid.

5. (Original) A film deposition apparatus according to claim 4,

wherein an inside of said transferring chamber is kept under a reduced pressure and said liquid phase film deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

6. (Original) A film deposition apparatus according to claim 4,

wherein said transferring chamber is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

7. (Currently Amended) A film deposition apparatus comprising:

- a stock chamber for loading or unloading a substrate;
- two transferring chambers each connected to said stock chamber through a gate;
- a vapor phase film deposition chamber connected to one of said two transferring chambers through a gate; and
- a liquid phase film deposition chamber connected to another said transferring chamber through a gate,

wherein said liquid phase film deposition chamber is provided with a mechanism for oxidizing an element belonging to Group 1 or 2 of the periodic table,

wherein said second mechanism includes an oxidization cell having a lid and an oxygen gettering agent,

wherein a period of time in which said oxygen gettering agent is oxidized is adjusted ~~encapsulated~~ by opening and closing said lid.

8. (Previously presented) A film deposition apparatus according to claim 7,

wherein an inside of one of said transferring chambers is kept under a reduced pressure and said liquid phase film deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

9. (Previously presented) A film deposition apparatus according to claim 7,

wherein one of said transferring chambers is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

10 (Currently Amended). A film deposition apparatus comprising:

- a stock chamber for loading or unloading a substrate;
- two transferring chambers each connected to said stock chamber through a gate;
- a vapor phase film deposition chamber connected to one of said two transferring chambers through a gate; and
- a liquid phase film deposition chamber connected to another said transferring chamber through a gate,

wherein said liquid phase film deposition chamber is provided with, via a piping, a mechanism for oxidizing an element belonging to Group 1 or 2 of the periodic table,

wherein said second mechanism includes an oxidization cell having a lid and an oxygen gettering agent,

wherein a period of time in which said oxygen gettering agent is oxidized is adjusted ~~encapsulated~~ by opening and closing said lid.

11. (Previously presented) A film deposition apparatus according to claim 10,

wherein an inside of one of said transferring chambers is kept under a reduced pressure and said liquid phase film deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

12. (Previously presented) A film deposition apparatus according to claim 10,

wherein one of said transferring chambers is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

13. (Currently Amended) A film deposition apparatus comprising:
a stock chamber for loading or unloading a substrata;
a transferring chamber for transferring said substrate; and
an EL material deposition chamber connected to said transferring chamber through a gate,
wherein said EL material deposition chamber is provided with a cell which contains an
element belonging to Group 1 or 2 of the periodic table,
wherein said second mechanism includes an oxidization cell having a lid and an oxygen
gettering agent,
wherein a period of time in which said oxygen gettering agent is oxidized is adjusted
eneapsulated by opening and closing said lid.

14. (Original) A film deposition apparatus according to claim 13,
wherein an inside of said transferring chamber is kept under a reduced pressure and said EL
material deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a
pressurized state.

15. (Original) A film deposition apparatus according to claim 13,
wherein said transferring chamber is connected to a calcining chamber through a gate, and
said calcining chamber is provided with a mechanism for turning said substrate upside down.

16. (Currently Amended) A film deposition apparatus comprising:
a stock chamber for loading or unloading a substrate;
two transferring chambers each connected to said stock chamber through a gate;

a vapor phase film deposition chamber connected to one of said two transferring chambers through a gate; and

an EL material deposition chamber connected to another said transferring chamber through a gate,

wherein said EL material deposition chamber is provided with a cell which contains an element belonging to Group 1 or 2 of the periodic table,

wherein said second mechanism includes an oxidization cell having a lid and an oxygen gettering agent,

wherein a period of time in which said oxygen gettering agent is oxidized is adjusted encapsulated by opening and closing said lid.

17. (Previously presented) A film deposition apparatus according to claim 16,

wherein an inside of one of said transferring chambers is kept under a reduced pressure and said EL material deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

18. (Previously presented) A film deposition apparatus according to claim 16,

wherein one of said transferring chambers is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

19-30. (Cancelled)

31. (Previously presented) A film deposition apparatus according to claim 1,
wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

32. (Previously presented) A film deposition apparatus according to claim 1,
wherein said liquid phase film deposition chamber is provided with a spin coater for forming an EL
layer.

33. (Previously presented) A film deposition apparatus according to claim 1,
wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL
layer.

34. (Previously presented) A film deposition apparatus according to claim 4,
wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

35. (Previously presented) A film deposition apparatus according to claim 4,
wherein said liquid phase film deposition chamber is provided with a spin coater for
forming an EL layer.

36. (Previously presented) A film deposition apparatus according to claim 4,
wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL
layer.

37. (Previously presented) A film deposition apparatus according to claim 7,

wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

38. (Previously presented) A film deposition apparatus according to claim 7,
wherein said liquid phase film deposition chamber is provided with a spin coater for forming an EL layer.

39. (Previously presented) A film deposition apparatus according to claim 7,
wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL layer.

40. (Previously presented) A film deposition apparatus according to claim 10,
wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

41. (Previously presented) A film deposition apparatus according to claim 10,
wherein said liquid phase film deposition chamber is provided with a spin coater for forming an EL layer.

42. (Previously presented) A film deposition apparatus according to claim 10,
wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL layer.

43. (Previously presented) A film deposition apparatus according to claim 13,

wherein said EL material deposition chamber is provided with a spin coater for forming an EL layer.

44. (Previously presented) A film deposition apparatus according to claim 13, wherein said EL material deposition chamber is provided with a nozzle for forming an EL layer.

45. (Previously presented) A film deposition apparatus according to claim 16, wherein said EL material deposition chamber is provided with a spin coater for forming an EL layer.

46. (Previously presented) A film deposition apparatus according to claim 16, wherein said EL material deposition chamber is provided with a nozzle for forming an EL layer.

47. (Previously presented) A film deposition apparatus according to claim 1, wherein said lid is opened and closed.

48. (Previously presented) A film deposition apparatus according to claim 4, wherein said lid is opened and closed.

49. (Previously presented) A film deposition apparatus according to claim 7, wherein said lid is opened and closed.

50. (Previously presented) A film deposition apparatus according to claim 10,

wherein said lid is opened and closed.

51. (Previously presented) A film deposition apparatus according to claim 13,
wherein said lid is opened and closed.

52. (Previously presented) A film deposition apparatus according to claim 16,
wherein said lid is opened and closed.

53. (Previously Presented) A film deposition apparatus according to claim 1,
wherein said second mechanism includes a heater.

54. (Previously Presented) A film deposition apparatus according to claim 4,
wherein said second mechanism includes a heater.

55. (Previously Presented) A film deposition apparatus according to claim 7,
wherein said second mechanism includes a heater.

56. (Previously Presented) A film deposition apparatus according to claim 10,
wherein said second mechanism includes a heater.

57. (Previously Presented) A film deposition apparatus according to claim 13,
wherein said second mechanism includes a heater.

58. (Previously Presented) A film deposition apparatus according to claim 16,
wherein said second mechanism includes a heater.

59. (Currently Amended) A film deposition apparatus comprising:
a liquid phase film deposition chamber,
wherein said liquid phase film deposition chamber is provided with a mechanism for
oxidizing an element belonging to Group 1 or 2 of the periodic table,
wherein said mechanism includes an oxidization cell having a lid and an oxygen gettering
agent,
wherein a period of time in which said oxygen gettering agent is oxidized is adjusted
encapsulated by opening and closing said lid.

60. (Previously Presented) A film deposition apparatus according to claim 59,
wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

61. (Previously Presented) A film deposition apparatus according to claim 59,
wherein said liquid phase film deposition chamber is provided with a spin coater for forming an EL
layer.

62. (Previously Presented) A film deposition apparatus according to claim 59,
wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL
layer.